



**Flexsys™ 3000**  
**High-Speed Die Bonder**



**A standard, flexible high-speed die bonder  
designed for the most demanding applications**



**Automation  
Tooling  
Systems**

At ATS, we build high-precision process and assembly systems for advanced packaging, multi-chip modules and optoelectronics. ATS Flexsys™ workcells accommodate multiple high-speed operations on a single platform to deliver higher production volumes and dramatically improved yields. With Flexsys™ you get the capability you need today, and the ability to scale up for tomorrow.

## Description

The ATS Flexsys™ 3000 High-Speed Die Bonder automates die placement and attach to achieve higher production volumes while improving yields. Designed to work with a wide range of tooling, these stand-alone or integrated systems provide maximum flexibility and throughput on a standard machine platform.

## Typical Applications

- In-package or chip-on-carrier assembly
- Epoxy die attach
- Thermal-compression bonding
- Flip chip bonding

## Specifications

Assembly Platform:	Air bearing and rail configurations with linear motors and encoders (Application dependant)
Operating Envelope:	X: 600 mm, Y: 900 mm, Z: 50 mm
Accuracy:	5 microns (Application dependant)
Controls:	PC-based machine controller with Windows HMI
Instrumentation:	GPIB and analog interfaces to industry-standard instrumentation
Safety Compliance:	OSHA, CSA and CE
Clean Room Compliance:	Clean room compatible to Class 100

## Options

- Force sensing
- Soldering
- Scalable for additional material handling
- Surface probing
- Vision inspection
- Material handling
  - Auer Boat loaders/unloaders
  - tape and reel
  - Gel-Paks®
  - waffle packs
  - JEDEC trays

## Features

- Automated material handling
- Vision-guided placement and alignment
- Fixture or pallet based
- Standard conveyor modules (SMEMA)
- Assembly line integration
- Bar code tracking (1D and 2D)
- Data-driven software design for maximum flexibility
- Industry-standard replacement parts for ease of maintenance
- Epoxy stamping to 50 microns

## Typical Products

- Multi-chip modules
- Transmitters, receivers and transceivers
- RF modules
- MUX and DEMUX components
- Switches
- Tunable devices
- Planar waveguides and arrays
- DWDM modules



Contact ATS directly for custom or product specific applications outside the scope of this document.



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ISO 9001 Registered QS 9000 - ISO 9002 Registered

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